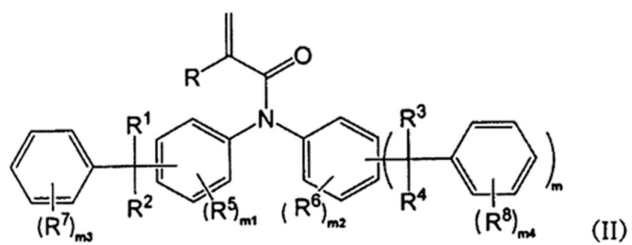
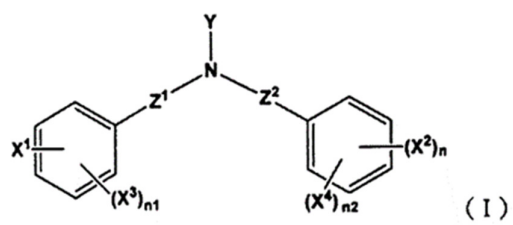


NOVEL (METH)ACRYLAMIDE POLYMER, RESIN COMPOSITION
CONTAINING SAME, AND MOLDED BODY THEREOF

ABSTRACT

The present invention provides a polymer, a resin composition containing the same, and a molded body thereof, having excellent heat resistance and dielectric properties, capable of being dissolved in an organic solvent at a high concentration, and having excellent compatibility with other thermoplastic resins and thermosetting resins. The polymer of the present invention has: a repeating unit derived from a polymerizable compound of the following formula (I) (in the formula X^1 and X^2 each independently represent a C7 to C20 alkyl group or a C7 to C20 alkoxy group, n represents 0 or 1, Z^1 and Z^2 each independently represent a single bond or a C1 to C3 alkylene group, X^3 and X^4 each independently represent an organic group or a halogeno group, n_1 and n_2 each independently represent any integer of 0 to 4, and Y represents a polymerizable functional group); and a repeating unit derived from a polymerizable compound of formula (II) (in the formula, R represents a hydrogen atom or a methyl group, R^1 to R^4 each independently represent any of a hydrogen atom, a C1 to C6 alkyl group, or a C1 to C6 alkoxy group, R^5 to R^8 each independently represent an organic group or a halogeno group, m_1 to m_4 each independently represent any integer of 0 to 4, and m represents 0 or 1).



[No Figure]